

Design of local exhaust ventilation for preventive maintenance in the semiconductor industry using CFD

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1. Background

- When the chemicals are remained or generated by-product in equipment, which causes defects the product thus maintenance tasks are necessary periodically
- The maintenance tasks are performed manually by workers
 - Replacement parts, troubleshooting and wiping out a chamber with an ethanol or de-ionized water soaked wiper
- At this time, there are potential risks that the maintenance workers might be exposed the reactant or by-products during the work. Additionally, the contaminants are released which may disperse in cleanroom, so workers who work surrounding area might be exposed as well [1, 2]

2. Objectives

- Design local exhaust ventilation(LEV) for maintenance tasks in order to improve working environment and protect worker's health in semiconductor manufacturing process
- The primary focus in designing the hood was convenience and undisturbance of the work

3. Methods

1) Experimental and numerical Model

- 300 mm semiconductor wafer fabrication facility, ISO class 5 (South Korea)
- Metallization process chamber was used
 - A cylindrical chamber : 600(d) x 100(h) mm

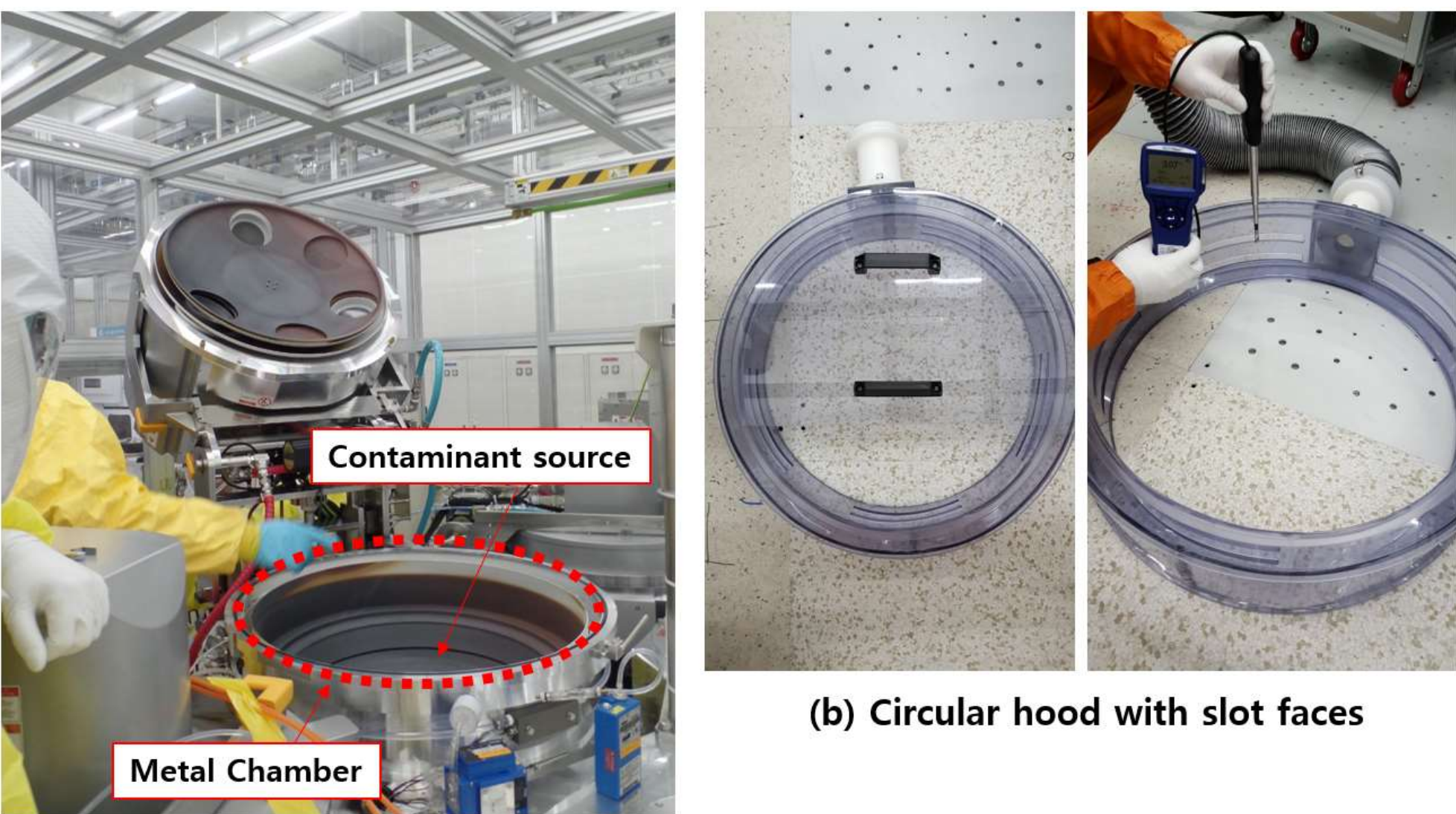
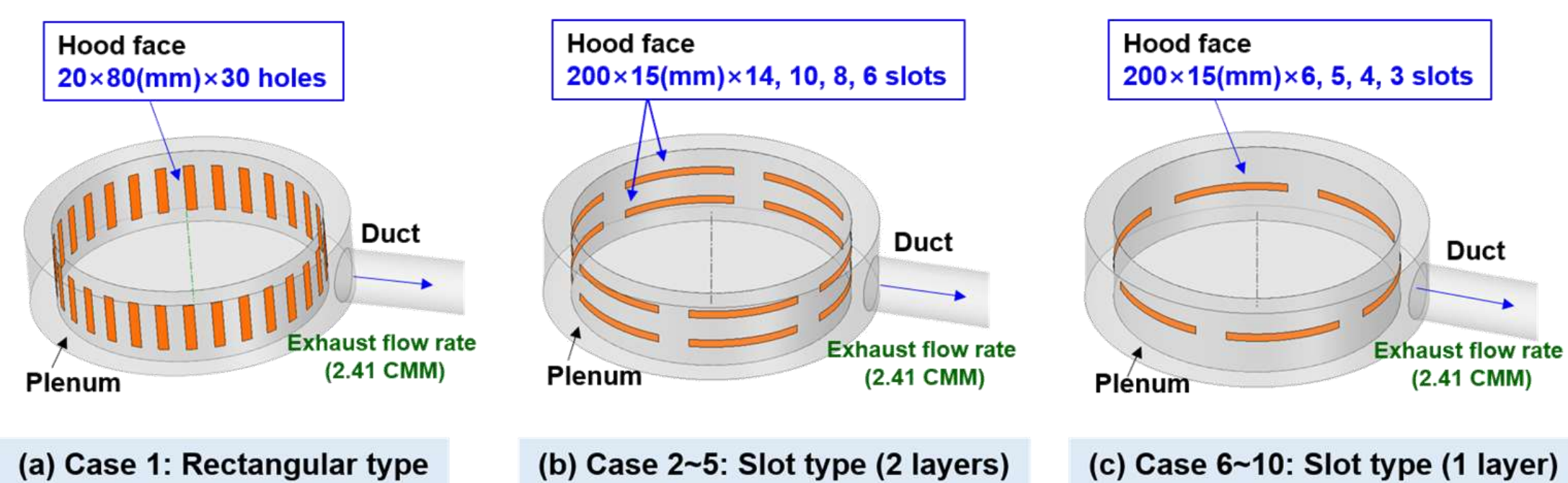


Figure 1. Metallization process chamber and test hood

- LEV : A cylindrical shape (same size with the chamber, D = 600 mm)

- To place on the chamber
 - Control the contaminants before disperse out of chamber
- The circular hood was made of acrylic were used in the experiments
- The measurements of face velocity
 - Hot-wire anemometer (TSI 9515) at 30 distributed points



2) Numerical method

- The commercial code : Fluent Ver. 19.2 (Ansys Inc.)
- Turbulence model : realizable k-ε model
- SIMPLE(Semi-Implicit Method for Pressure Linked Equations) algorithm

3) Boundary conditions

- Flow rate : 2.41 m³/min
- Capture efficiency (CE) = $(1 - M_{out}/M_g) \times 100(\%)$
 - M_g : the contaminants amount
 - M_{out} : the amount of dispersion to outside
 - The ratio of the captured contaminants to the total generated emission rate
 - Source : A metalloid that is a member of group 15 of the periodic table
 - uniformly released from a bottom of the chamber
- Mesh : 550,000~1,000,00

Table 1. Types and conditions of numerical analysis

Case	Type	Hood face number	Layer	Opening Dimensions		Flow rate (m ³ /min)
				W x L (mm)	Area(m ²)	
Case 1	Rectangle	30	1	80 x 20	0.048	2.41
Case 2	Slot	14	2	20 x 200	0.048	
Case 3	Slot	10	2	20 x 200	0.040	
Case 4	Slot	8	2	20 x 200	0.032	
Case 5	Slot	6	2	20 x 200	0.024	
Case 6	Slot	6	1	20 x 200	0.024	
Case 7	Slot	5	1	20 x 200	0.020	
Case 8	Slot	4	1	20 x 200	0.016	
Case 9	Slot	3	1	20 x 200	0.012	
Case 10	Slot	3	1	20 x 200	0.012	

4. Results

1) Comparison to numerical analysis and experimental results

- Overall simulation results agree quite well with the experiments data of measurement to the center line velocity on circular plenum surface
- The accuracy within 300 mm of the duct opening matched the experimental value within 20%

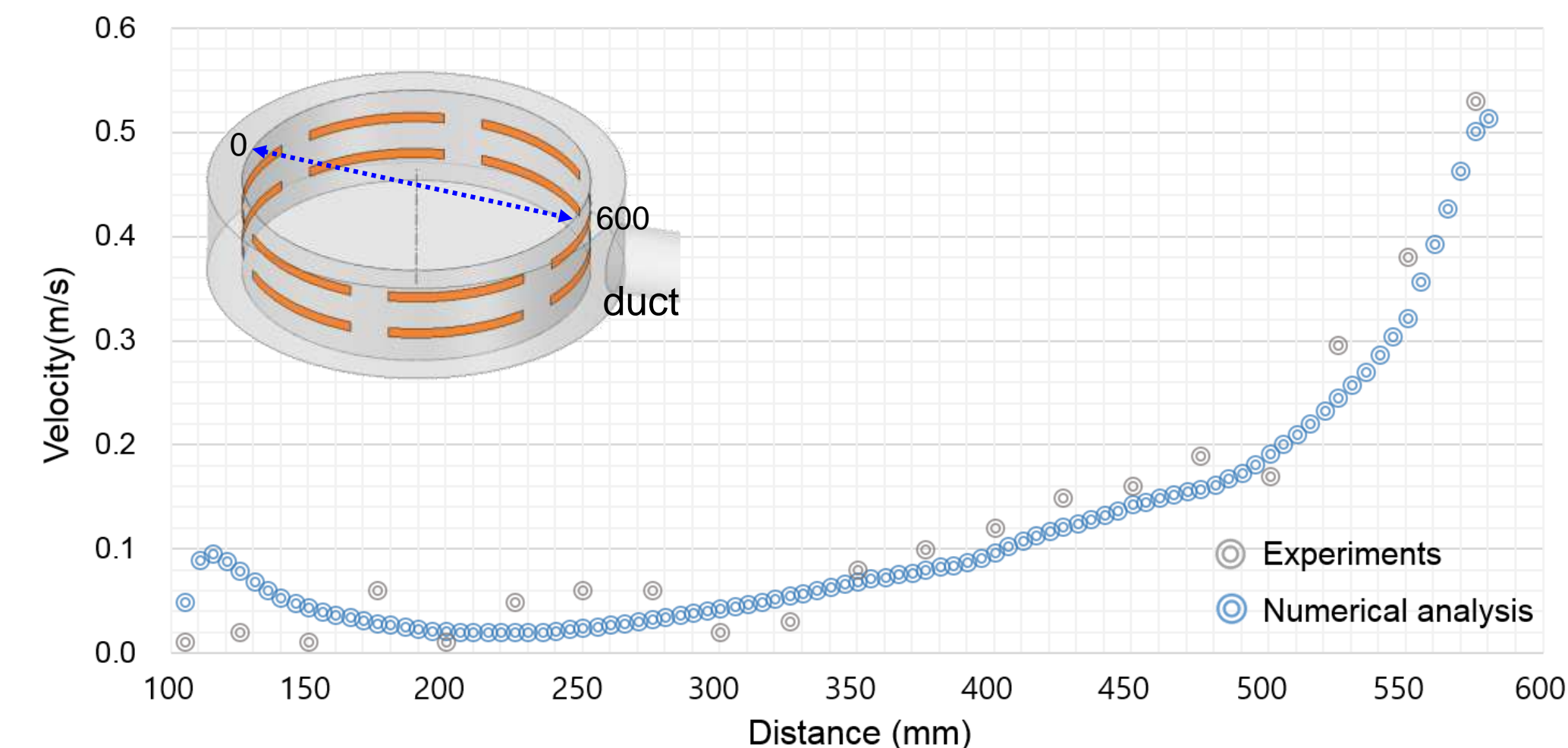
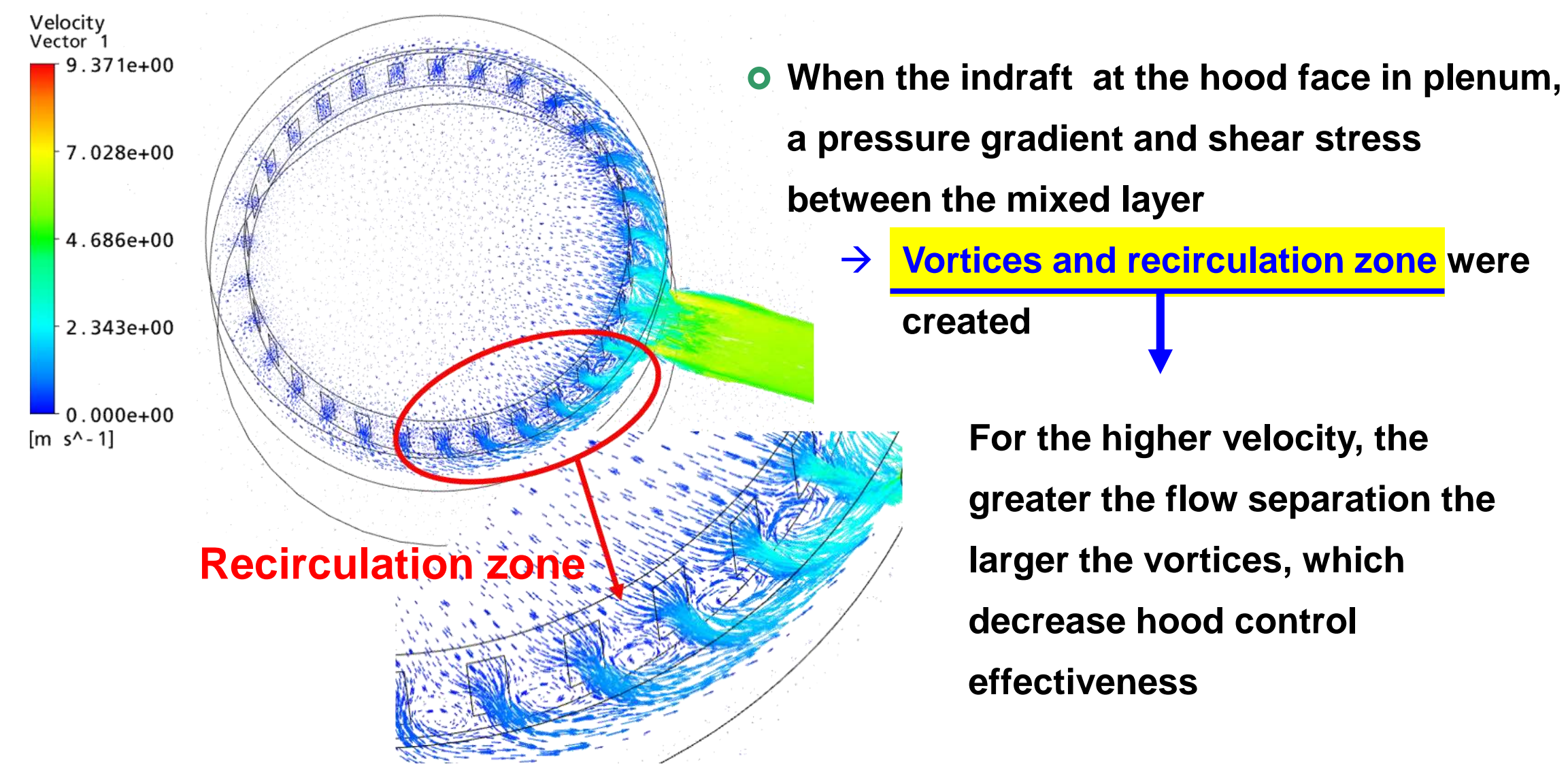


Figure 2. Comparison of the numerical and experimental results

2) Rectangular type opening

- The velocity of each hood face was different by location
 - The speed in the vicinity of the duct opening was up to 2.61 m/s, on the contrary, the minimum velocity opposite the duct opening was 0.12 m/s
 - The ratio of maximum and minimum velocity was 22.7



- A stagnation zone might occur at the vortex of the recirculation zone
 - It affects the hood performance and accumulates of pollutant in recirculation zone

3) Slot type opening

- The velocity distribution and capture efficiency were improved than rectangle face
 - Case 1 and 2 have a same area but they are significantly different
 - No recirculation zone in slot type and uniform air flow generated
 - Almost hood face velocity exceeded 0.5 m/s
- Efficiency to the number of slot
 - When the number of slot decreased, the face velocity were improved and uniformity were advanced
 - Case 5 and 6 (different layer with same area)
 - there were no significant differences in slot layer
 - when the 1 layer, the velocity exceeded 2.0 m/s (ratio of maximum and minimum velocity was not more than twice)

Table 2. Results of the simulation

Case	Type	Hood face number	Layer	Capture efficiency(%)	Mean velocity (m/s)	Velocity distribution (max/min)
Case 1	Rectangle	30	1	82.1%	0.816	22.65
Case 2	Slot	14	2	90.2%	1.185	6.08
Case 3	Slot	10	2	91.8%	1.401	3.80
Case 4	Slot	8	2	93.0%	1.795	2.92
Case 5	Slot	6	2	94.9%	2.420	1.96
Case 6	Slot	6	1	91.1%	2.366	1.57
Case 7	Slot	5	1	92.3%	2.859	1.36
Case 8	Slot	4	1	94.0%	3.571	1.26
Case 9	Slot	3	1	96.3%	4.802	1.27
Case 10	Slot	3	1	96.0%	4.784	1.11

5. Conclusions

- Slot hood had a higher capture efficiency than a rectangular hood
 - The slot hood provided uniform air flow and higher face velocity
 - There were no vortex in the plenum for slot, that is why slot had better efficiency than rectangular even though they had same face area
- The number of slot
 - the smaller the number of hood face, the higher the velocity and the efficiency
- When the face velocity is maintained more than 1.0 m/s,
 - the capture efficiency is above 90%

6. References

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